

Four Output Differential Buffer for PCle Gen 1 and Gen 2

ICS9DB403D

Description

The ICS9DB403 is compatible with the Intel DB400v2 Differential Buffer Specification. This buffer provides 4 PCI-Express Gen2 clocks. The ICS9DB403 is driven by a differential output pair from a CK410B+, CK505 or CK509B main clock generator.

Output Features

- 4 0.7V current-mode diff erential output pairs
- · Supports zero delay buffer mode and fanout mode
- · Bandwidth programming available
- 50-100 MHz operation in PLL mode
- 50-400 MHz operation in Bypass mode

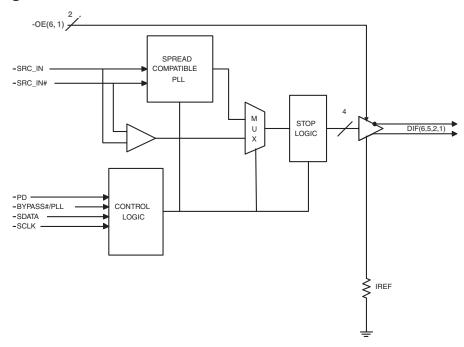
Features/Benefits

- Spread spectr um modulation toler ant, 0 to -0.5% do wn spread and +/- 0.25% center spread.
- Supports undriven differential outputs in PD# and SRC_STOP# modes for power management.

Key Specifications

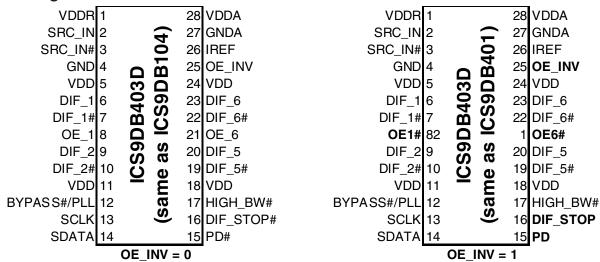
- Outputs cycle-cycle jitter < 50ps
- Outputs skew: 50ps
- Phase jitter: PCle Gen1 < 86ps peak to peak
- Phase jitter: PCle Gen2 < 3.0/3.1ps rms
- 28-pin SSOP/TSSOP pacakge
- Available in RoHS compliant packaging
- Supports Commercial (0 to +70°C) and Industrial (-40 to +85°C) temperature ranges

Functional Block Diagram



Note: Polarities shown for $OE_INV = 0$.

Pin Configuration



28-pin SSOP & TSSOP

Polarity Inversion Pin List Table

	OE_INV				
Pins	01				
8	OE_1	OE1#			
15	PD#	PD			
16	DIF_STOP#	DIF_STOP			
21	OE_6	OE6#			

Power Groups

Pin N	lumber	Description			
VDD	GND	Description			
1	4	SRC_IN/SRC_IN#			
5,11,18, 24	4	DIF(1,2,5,6)			
N/A	27	IREF			
28	27	Analog VDD & GND for PLL core			

Pin Decription When OE_INV = 0

	TIPLION WHEN OL		
PIN#	PIN NAME	PIN TYPE	DESCRIPTION
1V	DDR	PWR	3.3V power for differential input clock (receiver). This VDD should be treated
			as an analog power rail and filtered appropriately.
2	SRC_IN	IN	0.7 V Differential SRC TRUE input
3	SRC_IN#	IN	0.7 V Differential SRC COMPLEMENTARY input
4	GND	PWR	Ground pin.
5	VDD	PWR	Power supply, nominal 3.3V
6	DIF_1	OUT	0.7V differential true clock output
7	DIF_1#	OUT	0.7V differential Complementary clock output
80	E_1	IN	Active high input for enabling output 1.
80		IIN	0 =disable outputs, 1= enable outputs
9	DIF_2	OUT	0.7V differential true clock output
10	DIF_2#	OUT	0.7V differential Complementary clock output
11	VDD	PWR	Power supply, nominal 3.3V
12	BYPASS#/PLL	IN	Input to select Bypass(fan-out) or PLL (ZDB) mode
12	DTPASS#/PLL	IIN	0 = Bypass mode, 1= PLL mode
13	SCLK	IN	Clock pin of SMBus circuitry, 5V tolerant.
14	SDATA	I/O	Data pin for SMBus circuitry, 5V tolerant.
			Asynchronous active low input pin used to power down the device. The
15	PD#	IN	internal clocks are disabled and the VCO and the crystal osc. (if any) are
			stopped.
16	DIF_STOP#	IN	Active low input to stop differential output clocks.
47		18.1	3.3V input for selecting PLL Band Width
17	HIGH_BW#	IN	0 = High, 1= Low
18	VDD	PWR	Power supply, nominal 3.3V
19	DIF_5#	OUT	0.7V differential Complementary clock output
20	DIF_5	OUT	0.7V differential true clock output
01	05.0	INI	Active high input for enabling output 6.
21	OE_6	IN	0 =disable outputs, 1= enable outputs
22	DIF_6#	OUT	0.7V differential Complementary clock output
23	DIF_6	OUT	0.7V differential true clock output
24	VDD	PWR	Power supply, nominal 3.3V
0.5	OF INIV	INI	This latched input selects the polarity of the OE pins.
25	OE_INV	IN	0 = OE pins active high, 1 = OE pins active low (OE#)
			This pin establishes the reference for the differential current-mode output
	IDEE	01.7	pairs. It requires a fixed precision resistor to ground. 475ohm is the standard
26	IREF	OUT	value for 100ohm differential impedance. Other impedances require different
			values. See data sheet.
27	GNDA	PWR	Ground pin for the PLL core.
28	VDDA	PWR	3.3V power for the PLL core.
			F

Pin Decription When OE_INV = 1

PIN #	PIN NAME	PIN TYPE	DESCRIPTION		
			3.3V power for differential input clock (receiver). This VDD should be		
1V	DDR	PWR	treated as an analog power rail and filtered appropriately.		
2	SRC_IN	IN	0.7 V Differential SRC TRUE input		
3	SRC_IN#	IN	0.7 V Differential SRC COMPLEMENTARY input		
4	GND	PWR	Ground pin.		
5	VDD	PWR	Power supply, nominal 3.3V		
6	DIF_1	OUT	0.7V differential true clock output		
7	 DIF_1#	OUT	0.7V differential Complementary clock output		
			Active low input for enabling DIF pair 1.		
80	E1#	IN	1 =disable outputs, 0 = enable outputs		
9	DIF_2	OUT	0.7V differential true clock output		
10	DIF_2#	OUT	0.7V differential Complementary clock output		
11	VDD	PWR	Power supply, nominal 3.3V		
10	DVDACC#/DLL	INI	Input to select Bypass(fan-out) or PLL (ZDB) mode		
12	BYPASS#/PLL	IN	0 = Bypass mode, 1= PLL mode		
13	SCLK	IN	Clock pin of SMBus circuitry, 5V tolerant.		
14	SDATA	I/O	Data pin for SMBus circuitry, 5V tolerant.		
15	PD	IN	Asynchronous active high input pin used to power down the device.		
15	FD	IIN	The internal clocks are disabled and the VCO is stopped.		
16	DIF_STOP	IN	Active High input to stop differential output clocks.		
17	HIGH_BW#	IN	3.3V input for selecting PLL Band Width		
17			0 = High, 1= Low		
18	VDD	PWR	Power supply, nominal 3.3V		
19	DIF_5#	OUT	0.7V differential Complementary clock output		
20	DIF_5	OUT	0.7V differential true clock output		
21	OE6#	IN	Active low input for enabling DIF pair 6.		
			1 =disable outputs, 0 = enable outputs		
22	DIF_6#	OUT	0.7V differential Complementary clock output		
23	DIF_6	OUT	0.7V differential true clock output		
24	VDD	PWR	Power supply, nominal 3.3V		
25	OE_INV	IN	This latched input selects the polarity of the OE pins.		
			0 = OE pins active high, 1 = OE pins active low (OE#)		
			This pin establishes the reference for the differential current-mode		
26	IREF	OUT	output pairs. It requires a fixed precision resistor to ground. 475ohm is		
			the standard value for 100ohm differential impedance. Other		
			impedances require different values. See data sheet.		
27	GNDA	PWR	Ground pin for the PLL core.		
28	VDDA	PWR	3.3V power for the PLL core.		

Absolute Max

Symbol	Parameter	Min	Max	Units
VDDA/R	3.3V Core Supply Voltage		4.6	V
VDD	3.3V Logic Supply Voltage		4.6	V
V_{IL}	Input Low Voltage	GND-0.5		V
V _{IH}	Input High Voltage		V _{DD} +0.5V	V
Ts	Storage Temperature	-65	150	°C
Tambient	Commerical Operating Range	0	70	°C
Tallibletil	Industrial Operating Range	-40	85	°C
Tcase C	Tcase C ase Temperature		115	°C
	Input ESD protection			
ESD prot	human body model	2000		V

Electrical Characteristics - Clock Input Parameters

 T_A = Tambient for the desired operating range, Supply Voltage V_{DD} = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input High Voltage - DIF_IN	V _{IHDIF}	Differential inputs (single-ended measurement)	600	800	1150	mV	1
Input Low Voltage - DIF_IN	V_{ILDIF}	Differential inputs (single-ended measurement)	V _{SS} - 300	0	300	mV	1
Input Common Mode Voltage - DIF_IN	V _{COM}	Common Mode Input Voltage	300		1000	mV	1
Input Amplitude - DIF_IN	V_{SWING}	Peak to Peak value (single-ended measurement)	300		1450	mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2
Input Leakage Current	I _{IN}	$V_{IN} = V_{DD}, V_{IN} = GND$	-5		5	uA	1
Input Duty Cycle	d_{tin}	Measurement from differential wavefrom	45		55	%	1
Input Jitter - Cycle to Cycle	J_{DIFIn}	Differential Measurement	0		125	ps	1

¹ Guaranteed by design and characterization, not 100% tested in production.

²Slew rate measured through Vswing min centered around differential zero

Electrical Characteristics - Input/Supply/Common Output Parameters

 T_A = Tambient for the desired operating range, Supply Voltage V_{DD} = 3.3 V +/-5%

IA - I allibiciti for the acon	red operating	ialige, Supply Voltage V _{DD} = 3.3 V +/-3/8					
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input High Voltage	V _{IHSE}	a =	2		$V_{DD} + 0.3$	V1	
Input Low Voltage	V _{ILSE}	Single Ended Inputs, 3.3 V +/-5%	GND - 0.3		0.8	V	1
Input High Current	I _{IHSE}	$V_{IN} = V_{DD}$	-5		5	uA	1
	I _{IL1}	$V_{IN} = 0 \text{ V}$; Inputs with no pull-up resistors	-5			uA	1
Input Low Current	l.	V. = 0 V: Inpute with pull up registers	200				1
	I _{IL2}	$V_{IN} = 0$ V; Inputs with pull-up resistors Full Active, $C_L = Full$ load; Commerical	-200			uA	l l
	I _{DD3.3OPC}	Full Active, $C_L = Full load, Confinencal$ Temp Range		175	200	mA	1
9DB803 Supply Current	I _{DD3.3OPI}	Full Active, C _L = Full load; Industrial Temp Range		190	225	mA	1
		all diff pairs driven, C-Temp		50	60	mA	1
9DB803 Powerdown	I _{DD3.3PDC}	all differential pairs tri-stated, C-Temp		4	6	mA	1
Current	I _{DD3.3PDI}	all diff pairs driven, I-temp		55	65	mA	1
	וטים.3טטי	all differential pairs tri-stated, I-temp		6	8	mA	1
	I _{DD3.3OPC}	Full Active, C _L = Full load; Commerical		105	125	mA	1
9DB403 Supply Current		Temp Range			-		
1	I _{DD3.3OPI}	Full Active, C _L = Full load; Industrial Temp		115	150	mA	1
		Range all diff pairs driven, C-Temp		25	30	mA	1
9DB403 Powerdown	I _{DD3.3PDC}	all differential pairs tri-stated, C-Temp		25	30	mA mA	1
Current		all diff pairs driven, I-Temp		30	35	mA	1
	I _{DD3.3PDI}	all differential pairs tri-stated, I-Temp		3	4	mA	1
	F _{iPLL}	PCIe Mode (Bypass#/PLL= 1)	50	100.00	110	MHz	1
Input Frequency	F _{iBYPASS}	Bypass Mode ((Bypass#/PLL= 0)	33		400	MHz	1
Pin Inductance	L _{pin}	// ((=) passiii === 0)	- 55		7	nH	1
maadanido	C _{IN}	Logic Inputs, except SRC_IN	1.5		5	pF	1
Capacitance	C _{INSRC_IN}	SRC_IN differential clock inputs	1.5		2.7	рF	1,4
Supuonanio	C _{OUT}	Output pin capacitance	1.5		6	рF	1,4
		-3dB point in High BW Mode	2	3	4	MHz	1
PLL Bandwidth	BW	-3dB point in Flight BW Mode	0.7	1	1.4	MHz	1
PLL Jitter Peaking	t _{JPEAK}	Peak Pass band Gain		1.5	2	dB	1
2	OI LAIX	From V _{DD} Power-Up and after input clock		-		<u> </u>	
Clk Stabilization	T _{STAB}	stabilization or de-assertion of PD# to 1st			1	ms	1,2
	01/10	clock]	'-
Input SS Modulation	·	Allowable Frequency	-00		00	1,11-	4
Frequency	f _{MODIN}	(Triangular Modulation)	30		33	kHz	1
OE# Latency	tuance	DIF start after OE# assertion	1		3	cycles	1,3
OL# Latericy	t _{LATOE#}	DIF stop after OE# deassertion	'		J	cycles	۱,٥
Tdrive_SRC_STOP#	t _{DRVSTP}	DIF output enable after			10	ns	1,3
	-PUSSIL	SRC_Stop# de-assertion			10	113	٠,٠
Tdrive_PD#	t _{DRVPD}	DIF output enable after			300	us	1,3
Tfall	t _F	PD# de-assertion Fall time of PD# and SRC_STOP#			5	ns	1
Trise	ι _F	Rise time of PD# and SRC_STOP#			5		2
		Maximum input voltage				ns V	1
SMBus Voltage	V _{MAX}				5.5		
Low-level Output Voltage	V _{OL}	@ I _{PULLUP}	4.		0.4	V	1
Current sinking at V _{OL}	I _{PULLUP}	/May \/II = 0.45\ \-	4m			Α	1
SCLK/SDATA	t _{RSMB}	(Max VIL - 0.15) to			1000	ns	1
Clock/Data Rise Time SCLK/SDATA	- "-	(Min VIH + 0.15) (Min VIH + 0.15) to					
Clock/Data Fall Time	t _{FSMB}	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating	l .	,					
Frequency	f _{MAXSMB}	Maximum SMBus operating frequency			100	kHz	1,5
· · · · · · · · · · · · · · · · · · ·		ation, not 100% tosted in production				-	

¹Guaranteed by design and characterization, not 100% tested in production.

²See timing diagrams for timing requirements.

³Time from deassertion until outputs are >200 mV

⁴SRC_IN input

⁵The differential input clock must be running for the SMBus to be active

Electrical Characteristics - DIF 0.7V Current Mode Differential Pair

 T_A =Tambient; V_{DD} = 3.3 V +/-5%; C_L =2pF, R_S =33 Ω , R_P =49.9 Ω , R_{REF} =475 Ω

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Current Source Output Impedance	Zo ¹	3	000			Ω	1
Voltage High	VHigh	Statistical measurement on single ended signal using oscilloscope	660		850	mV	1,2
Voltage Low	VLow	math function.	-150		150	1110	1,2
Max Voltage	Vovs	Measurement on single ended			1150	mV	1
Min Voltage	Vuds	signal using absolute value.	-300				1
Crossing Voltage (abs)	Vcross(abs)		250		550	mV	1
Crossing Voltage (var)	d-Vcross	Variation of crossing over all edges			140	mV	1
Rise Time	t _r	$V_{OL} = 0.175V, V_{OH} = 0.525V$	175		700	ps	1
Fall Time	t _f	$V_{OH} = 0.525 V V_{OL} = 0.175 V$	175		700	ps	1
Rise Time Variation	d-t _r				125	ps	1
Fall Time Variation	d-t _f				125	ps	1
Duty Cycle	d _{t3}	Measurement from differential wavefrom	45		55	%	1
Clean Input to Output	t _{pdBYP}	Bypass Mode, $V_T = 50\%$	2500		5000	ps	1
Skew, Input to Output	t _{pdPLL}	PLL Mode V _T = 50%	-250		250	ps	1
Skew, Output to Output	t _{sk3}	V _T = 50%			50	ps	1
litter Cyale to evale		PLL mode			50	ps	1,3
Jitter, Cycle to cycle	t _{jcyc-cyc}	Additive Jitter in Bypass Mode			50	ps	1,3
		PCIe Gen1 phase jitter (Additive in Bypass Mode)		7	10	ps (pk2pk)	1,4,5
	t _{jphaseBYP}	PCIe Gen 2 Low Band phase jitter (Additive in Bypass Mode)		00	.1	ps (rms)	1,4,5
Jitter, Phase		PCIe Gen 2 High Band phase jitter (Additive in Bypass Mode)		0.3	0.5	ps (rms)	1,4,5
		PCIe Gen 1 phase jitter		40	86	ps (pk2pk)	1,4,5
	t _{jphasePLL}	PCIe Gen 2 Low Band phase jitter		1.5	3	ps (rms)	1,4,5
		PCIe Gen 2 High Band phase jitter		2.7/ 2.2	3.1	ps (rms)	1,4,5,6

¹Guaranteed by design and characterization, not 100% tested in production.

 $^{^{2}}$ I_{REF} = V_{DD}/(3xR_B). For R_B = 475 Ω (1%), I_{REF} = 2.32mA. I_{OH} = 6 x I_{REF} and V_{OH} = 0.7V @ Z_O=50 Ω .

³ Measured from differential waveform

⁴ See http://www.pcisig.com for complete specs

⁵ Device driven by 932S421C or equivalent.

⁶ First number is High Bandwidth Mode, second number is Low Bandwidth Mode

Clock Periods Differential Outputs with Spread Spectrum Enabled

Meas	urement									
Wi	ndow	1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
Sy	mbol	Lg-	-SSC	-ppm error	0ppm	+ ppm error	+SSC	Lg+		
		Absolute Period	Short-term Average	Long-Term Average	Period	Long-Term Average	Short-term Average	Period		
Definition		Minimum Absolute	Minimum Absolute	Minimum Absolute	Nominal	Maximum	Maximum	Maximum		
		Period	Period	Period					Units	Notes
	DIF 100	9.87400	9.99900	9.99900	10.00000	10.00100	10.05130	10.17630	ns	1,2,3
Je	DIF 133	7.41425	7.49925	7.49925	7.50000	7.50075	7.53845	7.62345	ns	1,2,4
Name	DIF 166	5.91440	5.99940	5.99940	6.00000	6.00060	6.03076	6.11576	ns	1,2,4
<u>=</u>	DIF 200	4.91450	4.99950	4.99950	5.00000	5.00050	5.02563	5.11063	ns	1,2,4
Signal	DIF 266	3.66463	3.74963	3.74963	3.75000	3.75038	3.76922	3.85422	ns	1,2,4
S	DIF 333	2.91470	2.99970	2.99970	3.00000	3.00030	3.01538	3.10038	ns	1,2,4
	DIF 400	2.41475	2.49975	2.49975	2.50000	2.50025	2.51282	2.59782	ns	1,2,4

Clock Periods Differential Outputs with Spread Spectrum Disabled

Meas	urement			-	-					
Wi	ndow	1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
Sy	mbol	Lg-	-SSC	-ppm error	0ppm	+ ppm error	+SSC	Lg+]	
		Absolute Period	Short-term Average	Long-Term Average	Period	Long-Term Average	Short-term Average	Period		
Def	inition	Minimum Absolute	Minimum Absolute	Minimum Absolute	Nominal	Maximum	Maximum	Maximum		
		Period	Period	Period					Units	Notes
	DIF 100	9.87400		9.99900	10.00000	10.00100		10.17630	ns	1,2,3
Je	DIF 133	7.41425		7.49925	7.50000	7.50075		7.62345	ns	1,2,4
Name	DIF 166	5.91440		5.99940	6.00000	6.00060		6.11576	ns	1,2,4
<u>a</u>	DIF 200	4.91450		4.99950	5.00000	5.00050		5.11063	ns	1,2,4
Signal	DIF 266	3.66463		3.74963	3.75000	3.75038		3.85422	ns	1,2,4
S	DIF 333	2.91470		2.99970	3.00000	3.00030		3.10038	ns	1,2,4

¹Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy specifications are guaranteed with the assumption that the input clock complies with CK409/CK410/CK505 accuracy requirements. The 9DB403/803 itself does not contribute to ppm error.

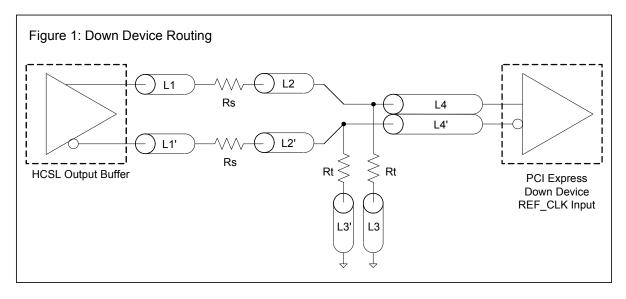
³ Driven by SRC output of main clock, PLL or Bypass mode

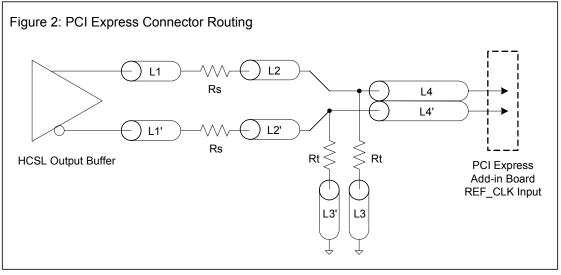
⁴ Driven by CPU output of CK410/CK505 main clock, **Bypass mode only**

SRC Reference Clock									
Common Recommendations for Differential Routing	Dimension or Value	Unit	Figure						
L1 length, route as non-coupled 50ohm trace	0.5 max	inch	1						
L2 length, route as non-coupled 50ohm trace	0.2 max	inch	1						
L3 length, route as non-coupled 50ohm trace	0.2 max	inch	1						
Rs	33	ohm	1						
Rt	49.9	ohm	1						

Down Device Differential Routing			
L4 length, route as coupled microstrip 100ohm differential trace	2 min to 16 max	inch	1
L4 length, route as coupled stripline 100ohm differential trace	1.8 min to 14.4 max	inch	1

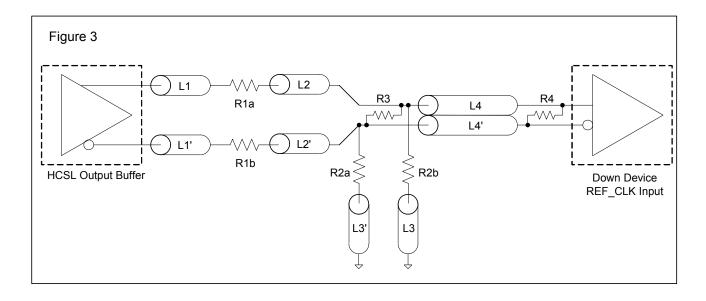
Differential Routing to PCI Express Connector			
L4 length, route as coupled microstrip 100ohm differential trace	0.25 to 14 max	inch	2
L4 length, route as coupled stripline 100ohm differential trace	0.225 min to 12.6 max	inch	2



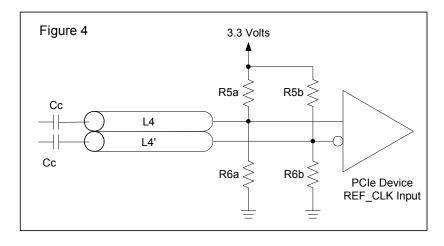


	Alternative Termination for LVDS and other Common Differential Signals (figure 3)										
Vdiff	Vp-p	Vcm	R1	R2	R3	R4	Note				
0.45v	0.22v	1.08	33	150	100	100					
0.58	0.28	0.6	33	78.7	137	100					
0.80	0.40	0.6	33	78.7	none	100	ICS874003i-02 input compatible				
0.60	0.3	1.2	33	174	140	100	Standard LVDS				

R1a = R1b = R1R2a = R2b = R2



Cable Connected AC Coupled Application (figure 4)							
Component	Value	Note					
R5a, R5b	8.2K 5%						
R6a, R6b	1K 5%						
Сс	0.1 μF						
Vcm	0.350 volts						



General SMBus serial interface information for the ICS9DB403D

How to Write:

- · Controller (host) sends a start bit.
- Controller (host) sends the write address DC_(h)
- ICS clock will acknowledge
- Controller (host) sends the begining byte location = N
- ICS clock will acknowledge
- Controller (host) sends the data byte count = X
- ICS clock will acknowledge
- Controller (host) starts sending Byte N through Byte N + X -1
- ICS clock will acknowledge each byte one at a time
- Controller (host) sends a Stop bit

How to Read:

- · Controller (host) will send start bit.
- Controller (host) sends the write address DC_(n)
- ICS clock will acknowledge
- Controller (host) sends the begining byte location = N
- ICS clock will acknowledge
- Controller (host) will send a separate start bit.
- Controller (host) sends the read address DD_(h)
- ICS clock will acknowledge
- ICS clock will send the data byte count = X
- ICS clock sends Byte N + X -1
- ICS clock sends Byte 0 through byte X (if X_(h) was written to byte 8).
- Controller (host) will need to adxnowledge each byte
- · Controllor (host) will send a not advnowledge bit
- · Controller (host) will send a stop bit

Ind	Index Block Write Operation										
Cor	ntroller (Host)		ICS (Slave/Receiver)								
Т	starT bit										
Slav	e Address DC _(h)										
WR	WRite										
	-		ACK								
Begi	nning Byte = N										
			ACK								
Data	Byte Count = X										
			ACK								
Begir	nning Byte N										
			ACK								
	\rightarrow	'te									
	\Diamond	X Byte	\Diamond								
	\rightarrow	×	\Q								
			\Q								
Byte	e N + X - 1										
			ACK								
Ps	toP bit										

Ind	ex Block Rea	ad	Operation		
Con	troller (Host)	IC	S (Slave/Receiver)		
Т	starT bit				
Slave	Address DC _(h)				
WR	WRite				
			ACK		
Begir	nning Byte = N				
			ACK		
RT	Repeat starT				
Slave	Address DD _(h)				
RD	ReaD				
			ACK		
		Data Byte Count = X			
	ACK				
			Beginning Byte N		
	ACK				
		g.	O		
	\Q	X Byte	O		
	\Diamond	×	\Q		
	\Q				
			Byte N + X - 1		
N	Not acknowledge				
Р	stoP it	b			

SMBus Table: Frequency Select Register, READ/WRITE ADDRESS (DC/DD)

Byt	te 0 Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	PD_Mode	PD# drive mode	RW	driven	Hi-Z	0
Bit 6	-	STOP_Mode	DIF_Stop# drive mode	RW	driven	Hi-Z	0
Bit 5	-	Reserved	Reserved	RW	Reserved		Х
Bit 4	-	Reserved	Reserved	RW	Reserved		X
Bit 3	-	Reserved	Reserved	RW	Reserved		X
Bit 2	-	PLL_BW#	Select PLL BW	RW	High BW	Low BW	1
Bit 1	-	BYPASS#	BYPASS#/PLL	RW	fan-out	ZDB	1
Bit 0	-	SRC_DIV#	SRC Divide by 2 Select	RW	x/2	1x	1

SMBus Table: Output Control Register

Ву	te 1	Pin#	Name	Control Function	Туре	0	1	Default
Bit 7	-		Reserved	Reserved	RW	Rese	erved	1
Bit 6	22,	23	DIF_6	Output Enable	RW	Disable	Enable	1
Bit 5	19,	20	DIF_5	Output Enable	RW	Disable	Enable	1
Bit 4	-		Reserved	Reserved	RW	Reserved		1
Bit 3	-		Reserved	Reserved	RW	Reserved		1
Bit 2	9,	10	DIF_2	Output Enable	RW	Disable	Enable	1
Bit 1	6,	7	DIF_1	Output Enable	RW	Disable	Enable	1
Bit 0	-		Reserved	Reserved	RW	Rese	erved	1

NOTE: The SMBus Output Enable Bit must be '1' AND the respective OE pin must be active for the output to run!

SMBus Table: OE Pin Control Register

By	te 2	Pin #	Name	Control Function	Type	0	1	Default
Bit 7		-	Reserved	Reserved	RW	Rese	Reserved	
Bit 6	22	,23	DIF_6	DIF_6 Stoppable with DIFSTOP	RW	Free-run	Stoppable	0
Bit 5	19,	,20	DIF_5	DIF_5 Stoppable with DIFSTOP	RW	Free-run	Stoppable	0
Bit 4		-	Reserved	Reserved	RW	Reserved		0
Bit 3		-	Reserved	Reserved	RW	Reserved		0
Bit 2	9.	.1	DIF_2	DIF_2 Stoppable with DIFSTOP	RW	Free-run	Stoppable	0
Bit 1	6	,7	DIF_1	DIF_1 Stoppable with DIFSTOP	RW	Free-run	Stoppable	0
Bit 0			Reserved	Reserved	RW	Rese	erved	0

SMBus Table: Reserved Register

Ву	te 3	Pin #	Name	Control Function	Type	0	1	Default	
Bit 7				Reserved				X	
Bit 6				Reserved					
Bit 5				Reserved				X	
Bit 4				Reserved				X	
Bit 3				Reserved				X	
Bit 2				Reserved				X	
Bit 1				Reserved				X	
Bit 0				Reserved				Х	

SMBus Table: Vendor & Revision ID Register

Byt	te 4 Pin	#	Name	Control Function	Type	0	1	Default
Bit 7			RID3		R	-	-	0
Bit 6	-		RID2	REVISION ID	R	•	-	0
Bit 5	-		RID1		R	1	-	1
Bit 4	-		RID0		R	-	-	1
Bit 3	-		VID3		R	ı	-	0
Bit 2	-		VID2	VENDOR ID	R	ı	-	0
Bit 1	-		VID1	VENDORID	R	-	-	0
Bit 0	-		VID0		R	-	-	1

SMBus Table: DEVICE ID

Byt	te 5	Pin #	Name	Control Function	า	Туре	0	1	Default
Bit 7		_		Device ID 7 (MSB)		RW			0
Bit 6		-		Device ID 6		RW			Х
Bit 5		-		Device ID 5		RW	Dovice ID	Х	
Bit 4		-		Device ID 4		RW	Device ID i	03 and 43	0
Bit 3		-		Device ID 3		RW			0
Bit 2		-		Device ID 2		RW	Hex for 9DB403		0
Bit 1		-		Device ID 1				1	
Bit 0		-		Device ID 0		RW			1

SMBus Table: Byte Count Register

Ву	te 6	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	-		BC7		RW	-	-	0
Bit 6	-		BC6		RW	-	-	0
Bit 5	-		BC5		RW	-	-	0
Bit 4	-		BC4	Writing to this register configures how	RW	-	-	0
Bit 3	-		BC3	many bytes will be read back.	RW	-	-	0
Bit 2	-		BC2		RW	-	-	1
Bit 1	-		BC1		RW	-	-	1
Bit 0	-		BC0		RW	-	-	1

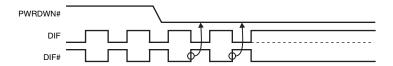
Note: Polarities in timing diagrams are shown OE_INV = 0. They are similar to OE_INV = 1.

PD#, Power Down

The PD# pin cleanly shuts off all clocks and places the device into a power saving mode. PD# must be asserted before shutting off the input clock or power to insure an order ly shutdown. PD is asynchronous activelow input for both powering down the device and powering up the device. When PD# is asserted, all clocks will be driven high, or tri-stated (depending on the PD# drive mode and Output control bits) before the PLL is shut down.

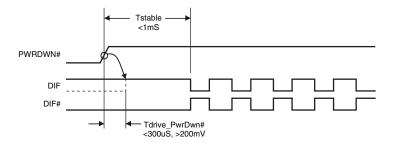
PD# Assertion

When PD# is sampled low by two consecutive rising edges of DIF#, all DIF outputs must be held High, or tri-stated (depending on the PD# drive mode and Output control bits) on the next High-Low transition of the DIF# outputs. When the PD# drive mode bit is set to '0', all clock outputs will be held with DIF dr iven High with 2 x I REF and DIF# tri-stated. If the PD# dr ive mode bit is set to '1', both DIF and DIF# are tr i-stated.



PD# De-assertion

Power-up latency is less than 1 ms . This is the time from de-asser tion of the PD# pin, or VDD reaching 3.3V, or the time from valid SRC_IN clocks until the time that stable clocks are output from the device (PLL Locked). If the PD# drive mode bit is set to '1', all the DIF outputs m ust driven to a voltage of >200 mV within 300 us of PD# de-asser tion.



SRC_STOP#

The SRC_STOP# signal is an active-low asynchronous input that cleanly stops and starts the DIF outputs. A valid clock must be present on SRC_IN for this input to work properly. The SRC_STOP# signal is de-bounced and must remain stable for two consecutive rising edges of DIF# to be recognized as a valid assertion or de-assertion.

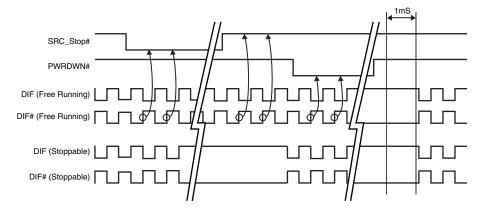
SRC STOP# - Assertion

Asserting SRC_STOP# causes all DIF outputs to stop after their next transition (if the control register settings allow the output to stop). When the SRC_STOP# drive bit is '0', the final state of all stopped DIF outputs is DIF = High and DIF# = Lo w. There is no change in output drive current. DIF is driven with 6XI_{REF} DIF# is not driven, but pulled low by the termination. When the SRC_STOP# drive bit is '1', the final state of all DIF output pins is Lo w. Both DIF and DIF# are not dr iven.

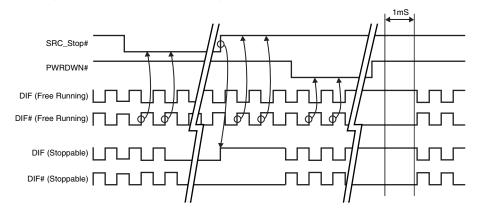
SRC_STOP# - De-assertion (transition from '0' to '1')

All stopped differential outputs resume nor mal operation in a glitch-free manner. The de-assertion latency to active outputs is 2-6 DIF clock periods, with all DIF outputs resuming simultaneously. If the SRC_ST OP# drive control bit is '1' (tri-state), all stopped DIF outputs must be driven High (>200 mV) within 10 ns of de-asser tion.

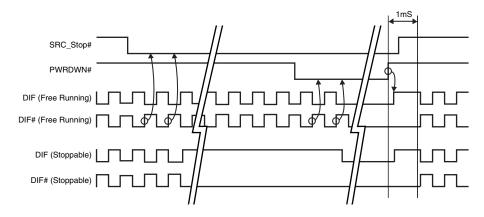
SRC_STOP_1 (SRC_Stop = Driven, PD = Driven)



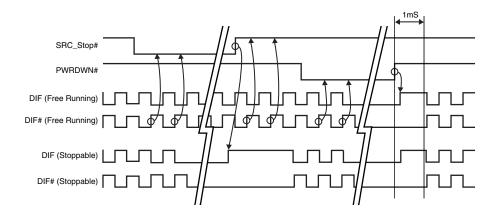
SRC_STOP_2 (SRC_Stop =Tristate, PD = Driven)



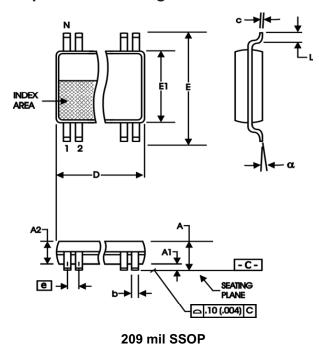
SRC_STOP_3 (SRC_Stop = Driven, PD = Tristate)



SRC_STOP_4 (SRC_Stop = Tristate, PD = Tristate)



28-pin SSOP Package Dimensions



209 mil SSOP

	In Millimeters		In Inches		
OVALDOL					
SYMBOL	COMMON DIMENSIONS		COMMON DIMENSIONS		
	MIN	MAX	MIN	MAX	
A-	-	2.00		.079	
A1	0.05		.002	-	
A2	1.65	1.85	.065	.073	
b	0.220	.38	.009.	015	
С	0.09	0.25	.0035	.010	
D	SEE VARIATIONS		SEE VAF	RIATIONS	
Е	7.408	.20	.291.	323	
E1	5.00	5.60	.197	.220	
е	0.65 BASIC		0.0256	BASIC	
L	0.550	.95	.022.	037	
N	SEE VARIATIONS		SEE VAF	RIATIONS	
α	0°	8°	0°	8°	

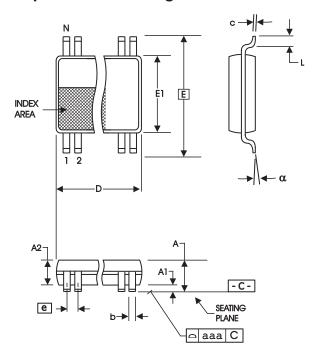
VARIATIONS

N	D mm.		D (inch)	
	MIN	MAX	MIN	MAX
28	9.90	10.50	.390	.413

Reference Doc.: JEDEC Publication 95, MO-150

10-0033

28-pin TSSOP Package Dimensions



4.40 mm. Body, 0.65 mm. Pitch TSSOP (173 mil) (25.6 mil)

	(1731111	11) (23.011	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		
	In Millimeters		In Inches		
SYMBOL	COMMON DIMENSIONS		COMMON DIMENSIONS		
	MIN	MAX	MIN	MAX	
Α		1.20		.047	
A1	0.05	0.15	.002	.006	
A2	0.80	1.05	.032	.041	
b	0.19	0.30	.007	.012	
С	0.09	0.20	.0035	.008	
D	SEE VARIATIONS		SEE VARIATIONS		
E	6.40 BASIC		0.252 BASIC		
E1	4.30	4.50	.169	.177	
е	0.65 BASIC		0.0256	0.0256 BASIC	
L	0.45	0.75	.018	.030	
N	SEE VAF	SEE VARIATIONS SEE VARIATIONS		RIATIONS	
α	0°	8°	0°	8°	

aaa VARIATIONS

N	D mm.		D (inch)	
	MINM	AX	MINM	AX
28	9.60	9.80	.378	.386

0.10

.004

Reference Doc.: JEDEC Publication 95, MO-153

10-0035

Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
9DB403DGLF	9DB403DGLF	Tubes	28-pin TSSOP	0 to +70° C
9DB403DGLFT	9DB403DGLF	Tape and Reel	28-pin TSSOP	0 to +70° C
9DB403DGILF	9DB403DGILF	Tubes	28-pin TSSOP	-40 to +85° C
9DB403DGILFT	9DB403DGILF	Tape and Reel	28-pin TSSOP	-40 to +85° C
9DB403DFLF	9DB403DFLF	Tubes	28-pin SSOP	0 to +70° C
9DB403DFLFT	9DB403DFLF	Tape and Reel	28-pin SSOP	0 to +70° C
9DB403DFILF	9DB403DFILF	Tubes	28-pin SSOP	-40 to +85° C
9DB403DFILFT	9DB403DFILF	Tape and Reel	28-pin SSOP	-40 to +85° C

[&]quot;LF" denotes Pb-free package, RoHS compliant

[&]quot;D" is the revision designator (will not correlate to datasheet revision)

Revision History

Rev.	Issue Date	Description	Page #
I	11/26/2008	Updated SMBus table - Byte0:Byte3.	11
J	2/6/2009	Added Industrial temp. specs and ordering information.	Various
K	7/13/2009	Updated general description and block diagram	1
		1. Clarified that Vih and Vil values were for Single ended inputs	
		2. Added separate Idd values for the 9DB403	
L	10/7/2009	3. Added Differential Clock input parameters.	Various
М	1/27/2011	Updated Termination Figure 4	10
		1. Update pin 1 pin-name and pin description from VDD to VDDR. This	
		highlights that optimal peformance is obtained by treating VDDR as in analog	
N	5/6/2011	pin. This is a document update only, there is no silicon change.	Various
Р	8/27/2012	Updated Vswing conditions to include "single-ended measurement"	5
Q	9/18/2012	Updated Byte 2, bits 1, 2, 5 and 6 per char review. Outputs can be programmed with Byte 2 to be Stoppable or Free-Run with DIF_Stop pin, not the OE pins.	12
R	11/1/2012	Updated Input-to-Output Skew max value (Bypass Mode condition only) from 4500ps to 5000ps per latest characterization data.	7

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For Sales

800-345-7015 408-284-8200 Fax: 408-284-2775

For Tech Support

408-284-6578 pcclockhelp@idt.com

Corporate Headquarters

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road San Jose, CA 95138 United States 800 345 7015 +408 284 8200 (outside U.S.)

Asia Pacific and Japan

Integrated Device Technology Singapore (1997) Pte. Ltd. Reg. No. 199707558G 435 Orchard Road #20-03 Wisma Atria Singapore 238877 +65 6 887 5505

Europe

IDT Europe, Limited Prime House Barnett Wood Lane Leatherhead, Surrey United Kingdom KT22 7DE +44 1372 363 339



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